



Wirebond Solution of Semiconductor IC Package through Modeling and Simulation

Frederick Ray I. Gomez^{1*}, Anthony R. Moreno¹ and Jonathan C. Pulido¹

¹Department of New Product Development and Introduction, STMicroelectronics, Inc., Calamba City, Laguna, 4027, Philippines.

Authors' contributions

This work was carried out in collaboration among all authors. All authors read and approved the final manuscript.

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ABSTRACT

This technical paper presents a study of wirebond selection highlighting the package electrical modeling and simulation done for semiconductor integrated circuit (IC) leadframe package (hereinafter referred to as Device Z) with different wirebond configurations: Gold 2N 1.3 mil, Gold 4N 1.3 mil, Copper 1.3 mil, Copper 1.2 mil, Copper 1.1 mil and Copper 1.0 mil. Package design, modeling and simulation are essentially important in the early stage of the package development, particularly at the package feasibility phase.

As Device Z is previously assembled with Gold 4N 1.3 mil wirebond configuration, this technical paper focused in determining the best alternative for Gold 4N 1.3 mil in wirebonding through package modeling and simulation. Statistical analysis reinforced the study to verify the trend and to check if there is significant statistical difference in the resistance, inductance and capacitance (hereinafter referred to as RLC) performance of the device given the different wirebond configurations. Cost analysis was crucial to determine the cost impact of using different wires.

Prioritizing the wirebond thickness and cost without sacrificing the electrical performance, Copper 1.1 mil would be the most suitable replacement for Gold 4N 1.3 mil wirebond configuration. However, since Copper 1.1 mil is not yet available in the market, Copper 1.2 mil could be used,

*Corresponding author: Email: f.i.gomez@ieee.org, frederick-ray.gomez@st.com;

with better electrical parameters. In addition, Copper wire offered significant cost improvement over its Gold counterpart. Computed cost per unit of Copper 1.3 mil is just 6% of the total cost of the Gold 4N 1.3 mil – that is 94% cost savings. Ultimately, Copper wire technology offers significant cost savings and could pave the way for more businesses in the plant.

Keywords: Package electrical modeling; simulation; wirebond; leadframe; semiconductor.

1. INTRODUCTION

With the latest technology and continuing trends, increasing market competition, and accelerating development in semiconductor industry [1-2], one should be flexible, resourceful and relatively quick in adapting to change, for the business to keep going. This is a major challenge for any semiconductor and technology company in order to maintain its competitive market value and position. Contrariwise, failure to provide customer expectation will result in eventual business failure.

Semiconductor package design, modeling and simulation are critical tools that help realize faster time-to-market development of semiconductor package. These capabilities play vital roles in the early stage of the package development, particularly at the package feasibility phase. Modeling, characterization and simulation are comprehensively used to evaluate and anticipate the new package performance and behavior, *i.e.* electrical performance and thermo-mechanical behavior. Fig. 1 illustrates examples of package models used for electrical modeling, characterization, and simulation.

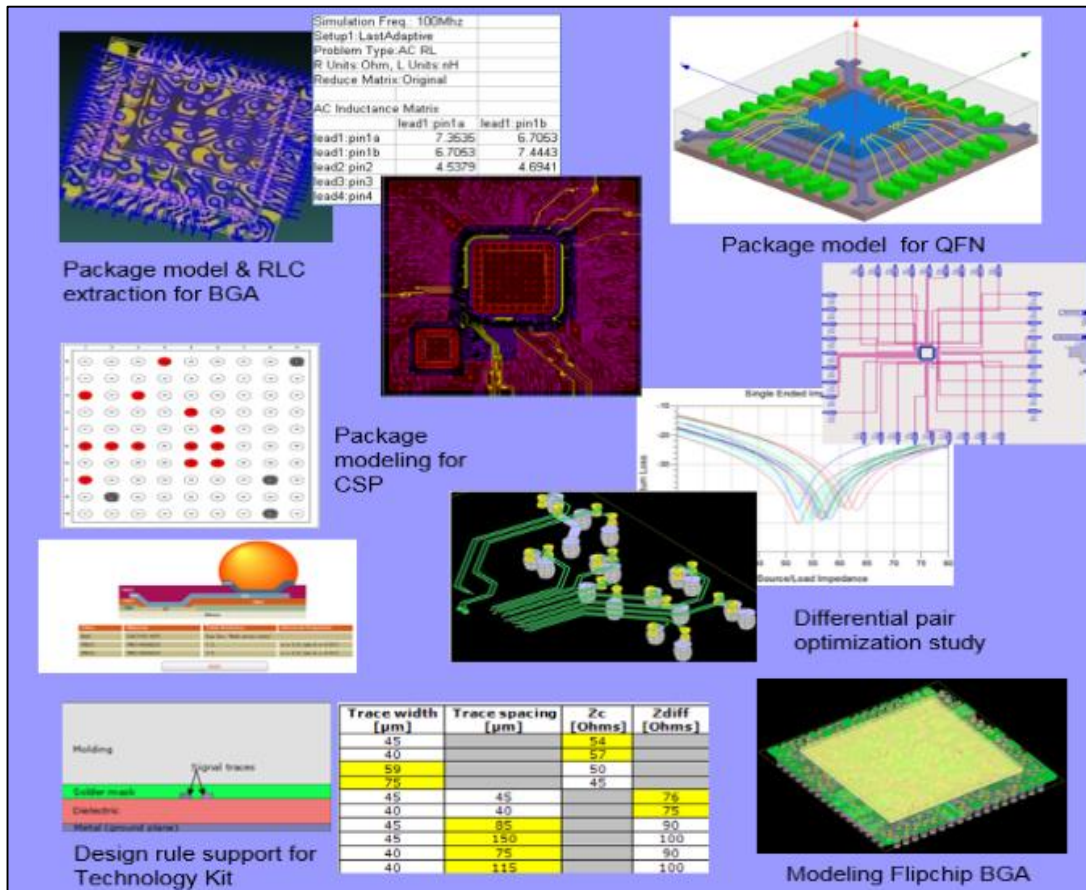


Fig. 1. Examples of package electrical modeling

A semiconductor integrated circuit (IC) device packaged in a standard leadframe configuration (hereinafter referred to as Device Z) previously utilized Gold 4N 1.3 mil wirebonding for power applications. However, the price of Gold (Au) has greatly increased in recent years, fueling the demand for high-volume wirebonding using other alternative like that of the Copper (Cu) wire, which can lead to significant cost savings due to lower raw material cost. Copper wire also offers better or higher electrical conductivity (reciprocal of resistivity) than its Gold counterpart, allowing more signals to flow in the circuit with less electrical loss at a given time. The development of Copper wire is one important achievement in the semiconductor industry, providing cost-efficient devices for wide range of power applications [3-4]. Moreover, one critical part of the development is at the package feasibility level wherein package design, modeling, characterization, and simulation take important roles.

Package electrical modeling study is essential to determine the package behavior and effect of different wirebond (or wirebond) configurations on Device Z: Gold 2N 1.3 mil, Gold 4N 1.3 mil, Copper 1.3 mil, Copper 1.2 mil, Copper 1.1 mil, and Copper 1.0 mil. As Device Z is previously assembled with Gold 4N 1.3 mil wirebond configuration, the ultimate goal of the study is to eventually determine the best alternative for Gold 4N 1.3 mil in wirebonding, prioritizing the wire size and cost without sacrificing the electrical performance.

2. REVIEW OF RELATED LITERATURE

Semiconductor package modeling, characterization and simulation are essentially carried out to evaluate, quantify and anticipate the new package performance and behavior. In electrical or electronic circuits and components, parasitic or inherent elements particularly the parasitic resistance, inductance and capacitance (RLC) should be minimized as these elements are unavoidable and not desirable for the components to have for its intended purpose. For instance, a resistor in Fig. 2 is designed to exhibit resistance, but also possesses unwanted parasitic inductance and capacitance [5]. Since parasitic RLC of the device cannot be completely eliminated, package designers will always strive to minimize it.

Different wirebond materials are available in the market, with each having their particular

electrical properties. Package electrical modeling is important to analyze the effect of different wires on the overall electrical performance of the semiconductor package.

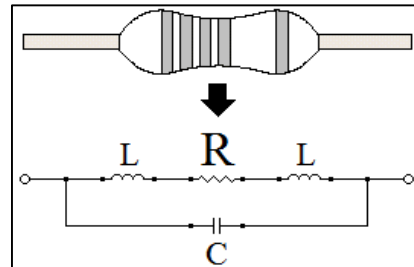


Fig. 2. Equivalent RLC circuit of a resistor

2.1 Package Electrical Parameters

As wirebond is a conductor, equivalent resistance of the wire could be computed using the expression in Eq. (1) for the sample wire in Fig. 3.

$$R = \rho l / A \quad (1)$$

where

- ρ = resistivity of the conductor or wire
- l = length
- A = cross-section area
- $A = \pi r^2$ (for round wire)
- r = radius

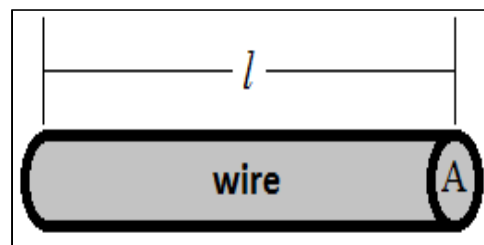


Fig. 3. Straight-wire conductor or wire, for resistance computation

Inductance value could be estimated using Eq. (2) for the straight-wire conductor. Increasing the diameter of a straight-wire conductor, like that of the wirebond, results in lower inductance.

$$L = 0.2l \cdot [\ln (4l / d) - 1] \quad (2)$$

where

- L = inductance in μH
- l = length of the conductor/wire in mm
- d = diameter of the conductor/wire in mm

Eq. (3) gives the simplified expression for the capacitance of a thin straight wire, for this case the wirebond.

$$C = (2\epsilon\pi l) / [\ln(l/r)] \quad (3)$$

where

- ϵ = absolute permittivity of the dielectric material
- l = length of the conductor/wire
- r = radius of the conductor/wire

2.2 Wirebonding Process Overview

Wirebonding is the method of making electrical connections between the silicon die and its packaging during semiconductor device assembly manufacturing, using very fine bonding wires. Fig. 4 illustrates the overview of the assembly wirebonding process. It is worth noting that wirebonding process varies also with the product and the technology [1,4,6]. Wirebonding

could also be used to connect any semiconductor device or integrated circuit (IC) to other electronic device or to connect from one printed circuit board (PCB) to another.

2.3 Copper Wire versus Gold Wire

Gold (Au) wire has been the most widely used wire in wirebonding process. However, in recent years the price of Gold has greatly increased, fueling the demand for high-volume wirebonding using Copper wire, which can lead to significant cost savings due to lower raw material cost. Aside from being cost-efficient, Copper wire exhibits lower resistance [3,4,7] in Fig. 5, which allows more signals to flow and less electrical loss at a given time.

With the discussion on Copper wire vs Gold wire, the challenge now is to determine the suitable replacement for Gold 4N 1.3 mil in wirebonding, based on the electrical performance through package modeling and simulation.

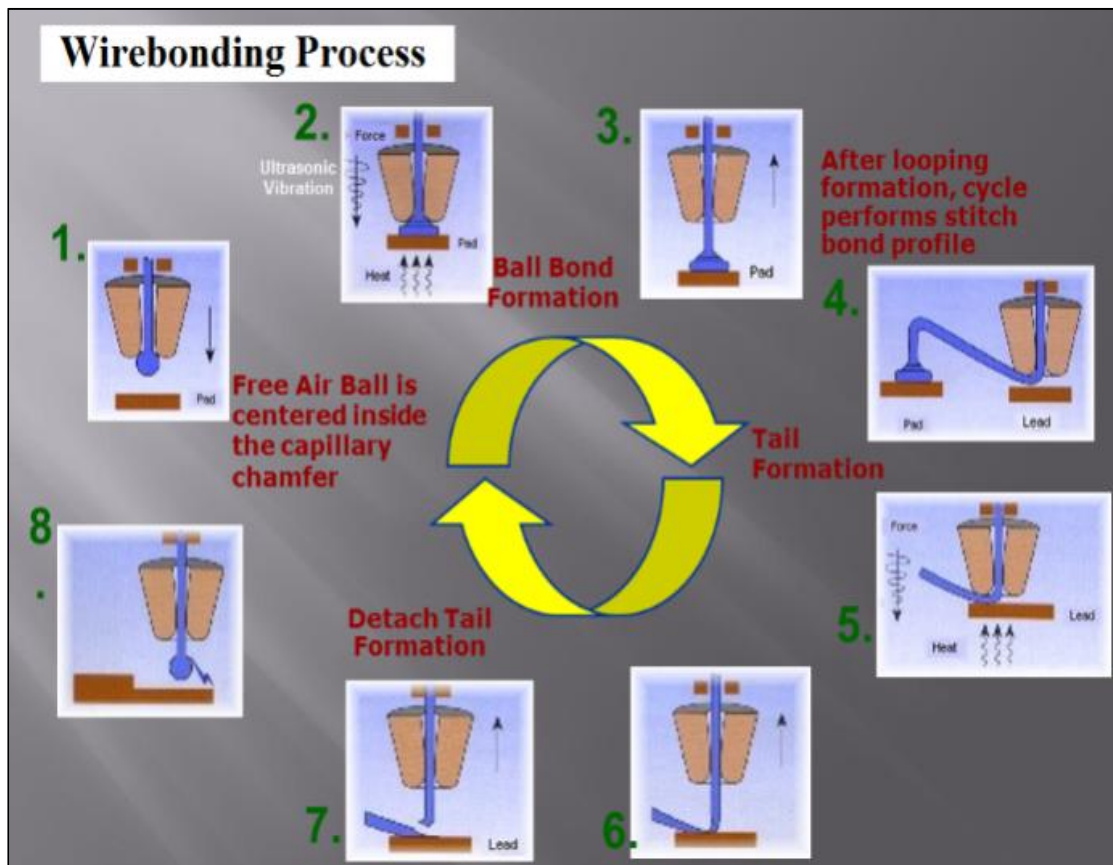


Fig. 4. Wirebonding process mechanism

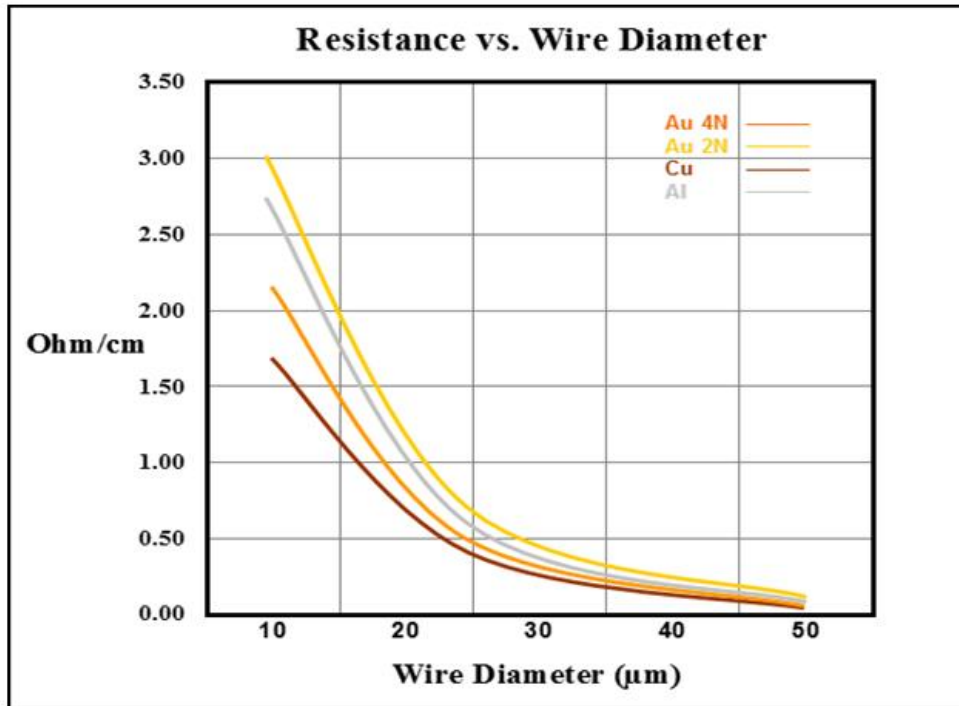


Fig. 5. Wirebond resistance versus size [7]

3. METHODOLOGY

Different wirebond models exist in package electrical modeling depending on the complexity of the design. Wirebond 3D model (cross-sectional view) in Fig. 6 was used for the study of Device Z, with parameters in Table 1 initially determined by the stakeholders.

The electronic design automation (EDA) software tool [8] used has the option to run Perl script that enables faster 3D model generation from 2D drawing of another computer-aided design (CAD) software tool [9] in Fig. 7 to the 3D equivalent model in Fig. 8.

To minimize wirebond electrical loss of Device Z and to have better electrical performance, RLC should be kept at minimal. As earlier discussed, the objective of the package electrical modeling study is to determine the package behavior and effect of different wirebond configurations on the device.

The models were analyzed at DC (direct current) for the DC resistance measurement and at AC (alternating current) with sample application frequency of 1.65 MHz for the RLC extraction. Total 3D wire length is computed based on the 2D length in Table 2 and the 3D wirebond parameters in Table 1.

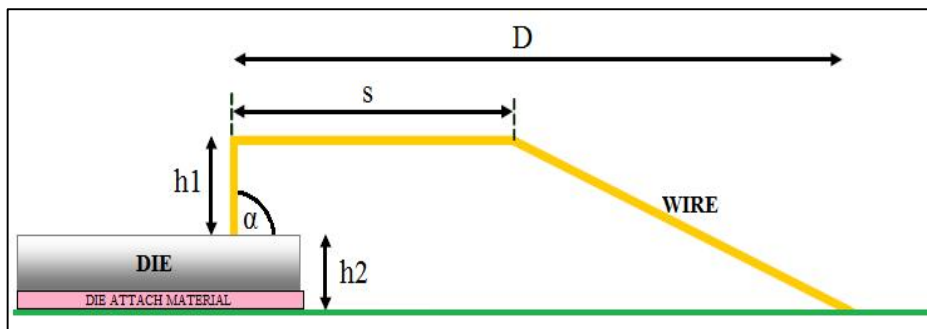
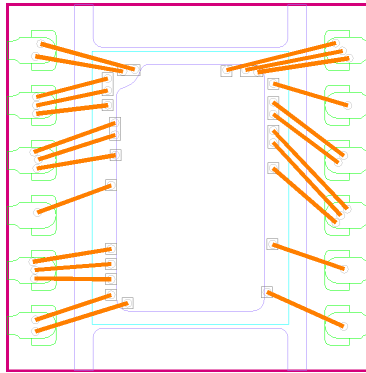


Fig. 6. Wirebond model

Table 1. Wirebond 3D model parameters

Wirebond parameter	Value		
Material	Gold 2N	Gold 4N	Copper
Conductivity, σ	31×10^6	43×10^6	58×10^6 S/m
Size/Diameter	1.3 mil	1.3 mil	1.0/1.1/1.2/1.3 mil
2D length, D	See Table 2		
Alpha angle, α	90 degrees		
Span length, s	60% of D		
Loop height, h1	0.130 mm		
Die + die attach thickness, h2	0.170 mm		

**Fig. 7. Mount and bonding diagram 2D model of device Z****Table 2. Wirebond 3D length**

WB	2D length, D (mm)	3D length (mm) ¹
bw1_1	0.799	1.071
bw1_2	0.728	1.008
bw2_1	0.603	0.900
bw2_2	0.597	0.894
bw2_3	0.588	0.887
bw3_1	0.706	0.989
bw3_2	0.660	0.949
bw3_3	0.652	0.942
bw4	0.644	0.935
bw5_1	0.649	0.940
bw5_2	0.626	0.920
bw5_3	0.628	0.921
bw6_1	0.653	0.942
bw6_2	0.791	1.064
bw7	0.689	0.974
bw8	0.621	0.916
bw9_1	0.680	0.966
bw9_2	0.814	1.085
bw9_3	0.883	1.147
bw10_1	0.665	0.953
bw10_2	0.725	1.005
bw11	0.637	0.929
bw12_1	0.758	1.035
bw12_2	0.808	1.079
bw12_3	0.920	1.180
Total 3D Wirebond Length		24.631 mm

¹Computed along with Table 1 parameters

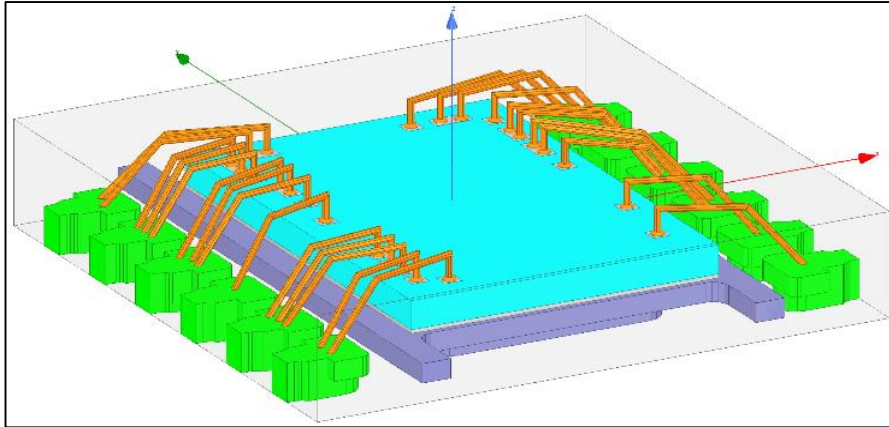


Fig. 8. Package 3D model of device Z

The computed total 3D wire length will then be used for the cost analysis of all wirebond configurations.

4. RESULTS AND DISCUSSION

Package modeling simulation results and statistical analysis are presented in terms of the RLC performance. Cost analysis was done to determine the impact in cost of using Copper and Gold wires.

4.1 RLC Performance

To minimize the electrical loss and to have better electrical performance, RLC should be minimized. Among the three wirebond materials with 1.3 mil diameter, Copper has the highest conductivity, σ , with 58,000,000 siemens/m (and the lowest resistivity, ρ), thus having the least R value for all signal nets in Fig. 9. Gold 2N conductivity is 31,000,000 S/m while Gold 4N has 43,000,000 S/m conductivity. Furthermore, signal nets with Copper 1.3 mil wires have the lowest resistance values compared to Copper 1.2 mil, 1.1 mil and 1.0 mil.

Main factor for the lower resistance value of Copper 1.3 mil is the larger wirebond cross-sectional area or the wirebond. Note that resistance R_{AC} at high frequency (or AC) is higher than the resistance R_{DC} at DC because of skin effect. As frequency goes up, the electric current tends to avoid travelling through most of the conductor's cross-sectional area. Smaller cross-sectional area results in higher resistance. Relationship between DC and AC resistance can be estimated using Eq. (4), with R_{DC} expressed in Eq. (1).

$$R_{AC} = R_{DC} \cdot k \cdot \sqrt{f} \quad (4)$$

where

k is the wire gage factor and f is frequency in MHz

Parasitic inductance performance of signal nets with different wirebond materials is given in Fig. 10. It can be noted that inductance is not dependent on the conductivity of the material, therefore signal nets with 1.3 mil wirebond diameter has the same self-inductance regardless of the wirebond material.

Increasing the wire diameter results in lower inductance. The trend could be verified also using Eq. (2). Finally, signal nets with 1.3 mil wirebonds have the lowest self-inductance compared to 1.2 mil, 1.1 mil and 1.0 mil.

Just like that of the inductance, parasitic capacitance is also not dependent on the conductivity of the material. Hence, signal nets with 1.3 mil wirebond diameter in Fig. 11 have the same self-capacitance regardless of the wirebond material.

Self-capacitance of a signal net is the total equivalent self-capacitance of the lead and wirebonds connected to it. Capacitance value increases as the area of the conductor increases, as depicted in Eq. (3). Copper 1.0 mil has the lowest parasitic capacitance performance among all wires.

Statistical analysis using SAS-JMP [10] was also done to verify the trend and to check if there is significant statistical difference in the RLC

performance of Device Z with different wirebond configuration. Among the three electrical properties, resistance has the most significant effect. The effect on self-capacitance is not significant although results showed that decreasing wirebond diameter decreases the self-capacitance. To minimize the electrical loss and to have better electrical performance, parasitic RLC should be minimized. With the

results, Copper 1.3 mil configuration has the best electrical performance.

4.2 Wirebond Cost Analysis

Analysis was done to compare the cost impact of using Copper wires versus the Gold wires. Table 3 shows the cost per unit for different wirebond material.

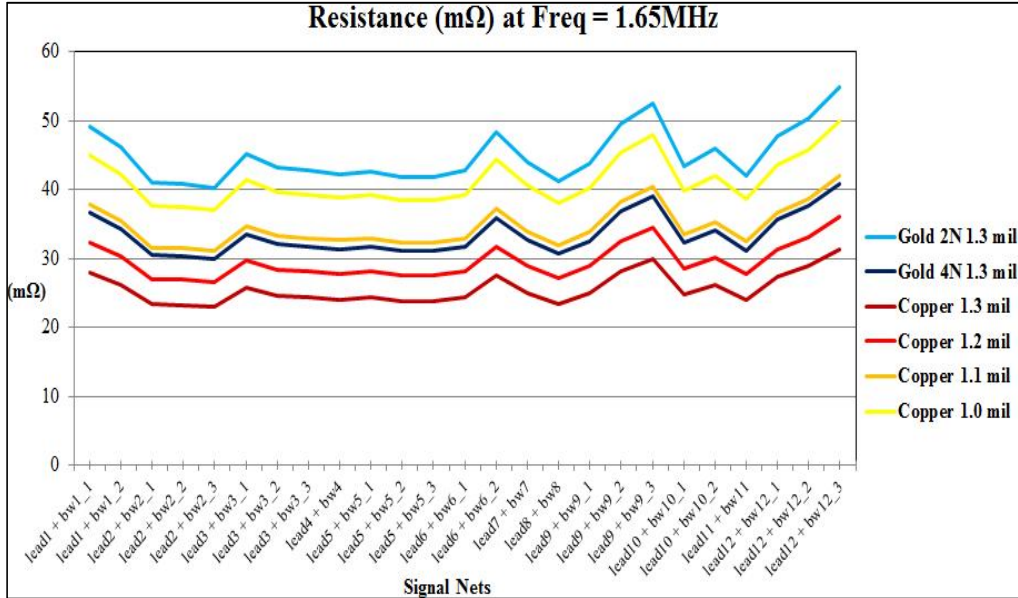


Fig. 9. Resistance comparison of signal nets with different wires

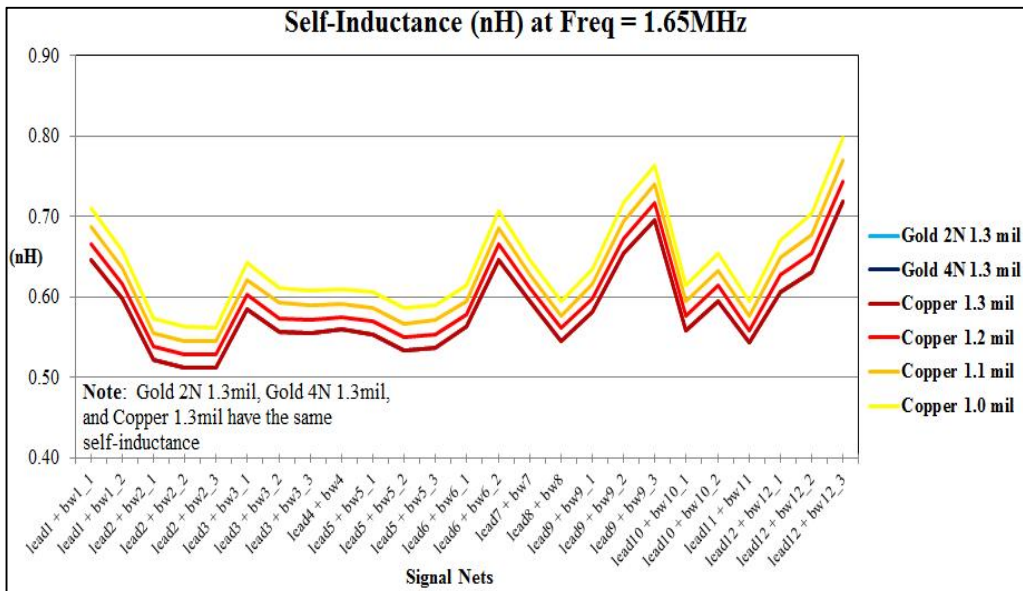


Fig. 10. Inductance comparison of signal nets with different wires

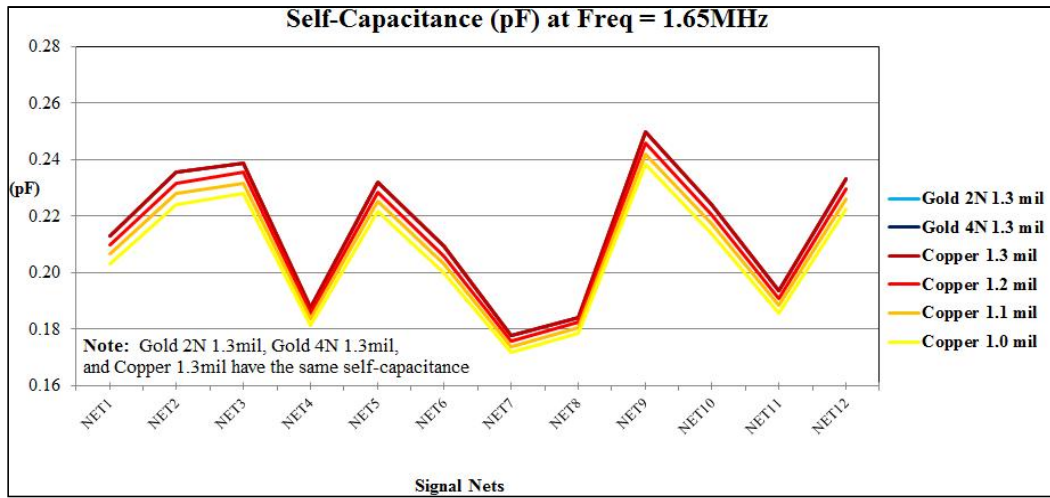


Fig. 11. Capacitance comparison of signal nets with different wires

Table 3. Wirebond cost per unit

Wirebond material	Cost per unit ^{1,2} (In comparison with Gold 4N)
Gold 4N 1.3 mil	100.00% – Reference
Gold 2N 1.3 mil	~100.00%
Copper 1.3 mil (CuPd)	6.00%
Copper 1.2 mil (CuPd)	6.00%
Copper 1.2 mil (Bare Cu)	2.32%
Copper 1.0 mil (Bare Cu)	1.85%

¹ Cost per unit in \$ intentionally not given; ² For total wirebond length of 24.631 mm

With Gold 4N 1.3 mil as the price reference, the cost of using CuPd (Copper wire coated with Palladium) 1.3 mil is just 6% of the cost of the Gold wire. For the bare Copper 1.0 mil, only 1.85% of the total Gold wire cost. Clearly, Copper wire technology offers massive cost savings and could pave way for more businesses in the plant.

5. CONCLUSIONS AND RECOMMENDATION

A comprehensive study of package electrical modeling and simulation was showcased for Device Z with different wirebond configurations: Gold 2N 1.3 mil, Gold 4N 1.3 mil, Copper 1.3 mil, Copper 1.2 mil, Copper 1.1 mil and Copper 1.0 mil. The models were analyzed at DC and AC for the RLC extraction.

Among the three electrical properties, resistance has the most significant effect. The effect on self-capacitance is not significant although results show that decreasing wirebond size decreases the self-capacitance value. To minimize the electrical loss and to have better electrical

performance, RLC should be minimized. As explained and shown in the results, Copper 1.3 mil wirebond configuration has the best electrical performance in terms of minimizing RLC.

Based on the technical data from one of the wirebond suppliers [11], Gold 4N 1.3 mil and Copper 1.1 mil have the closest (and the same) fusing currents with 0.85 A. Although Gold 4N 1.3 mil has slightly lower resistance values than Copper 1.1 mil, still their results are comparable and not significantly different. Prioritizing the wirebond thickness without sacrificing the electrical performance, Copper 1.1 mil would be the best replacement for Gold 4N 1.3 mil wirebond configuration. However, since Copper 1.1 mil is not yet available in the market, Copper 1.2 mil could be used, with better electrical parameters.

Copper wire offered significant cost improvement over its Gold counterpart. Computed cost per unit of Copper 1.3 mil (CuPd) is just 6% of the total cost of the Gold 4N 1.3 mil, with total wire length of 24.63 mm. Moreover, Copper 1.0 mil (bare

Cu) is just 1.85% of the total cost of the Gold 4N 1.3 mil reference – that is 98.15% cost savings. Ultimately, Copper wire technology offers massive cost savings and could pave the way for more businesses in the plant.

For future works, Silver (Ag) wires and Silver-alloy wires could be explored and studied for package modeling, cost analysis, and for manufacturability.

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COMPETING INTERESTS

Authors have declared that no competing interests exist. The products used for this research are commonly and predominantly use products in our area of research and country. There is absolutely no conflict of interest between the authors and producers of the products because we do not intend to use these products as an avenue for any litigation but for the advancement of knowledge. Also, the research was not funded by the producing company rather it was funded by personal efforts of the authors.

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